

ST3DV520

High bandwidth analog switch with 16-to-8 bit MUX/DEMUX

Preliminary Data

Features

■ Low R_{ON}: 5.5 Ω typical

V_{CC} operating range: 3.0 to 3.6 V
 Low current consumption: 20 µA

■ ESD HBM model: > 2 kV

■ Channel on capacitance: 7.5 pf typical

■ Switching time speed: 9 ns

Near to zero propagation delay: 250 psVery low cross talk: -40 db at 250 MHz

■ Bit-to-bit skew: 200 ps

> 450 MHz -3db typical bandwidth

■ Package: QFN56

Pb free



Description

The ST3DV520 is a 16-to-8 bit bidirectional multiplexer/demultiplexer low R_{ON} and high bandwidth switch suitable for analog video applications.

The ST3DV520 supports high definition (HD) analog video switching standards and is also suitable for general purpose switching that requires high signal integrity.

The device is designed for very low crosstalk, low bit-to-bit skew and low I/O capacitance. The signal from each input is multiplexed into one of two selected outputs while the unselected switch goes to HI-Z status.

Table 1. Device summary

Order code	Package	Packing
ST3DV520QTR	QFN56 Tape and re	

Pin description ST3DV520

1 Pin description

Figure 1. Pin connection (top through view)

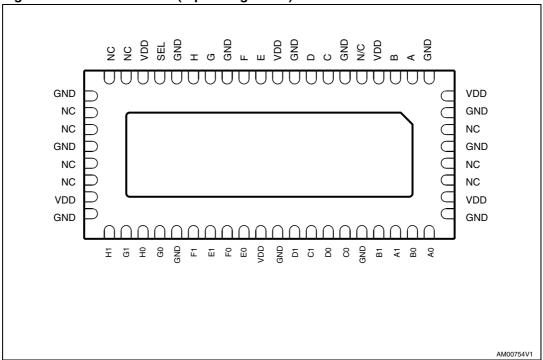


Table 2. Pin description

Pin number	Symbol	Name and function			
2, 3, 7, 8, 11, 12, 14, 15	A, B, C, D, E, F, G, H	8 bit bus			
31, 32, 36, 37, 42, 43, 47, 48	A0, B0, C0, D0, E0, F0, G0, H0	8 bit multiplexed to bus 0			
29, 30, 35, 40, 41, 45, 46	A1, B1, C1, D1, E1, F1, G1, H1	8 bit multiplexed to bus 1			
17	SEL	Bus switch selection			
5, 19, 20, 22, 23, 25, 26, 51, 52, 54	N/C	Not connected			
4, 10, 18, 27, 38, 50, 56	V_{DD}	Supply voltage			
1, 6, 9, 13, 16, 21, 24, 28, 33, 39, 44, 49, 53, 55	GND	Ground			

ST3DV520 Pin description

Figure 2. Input equivalent circuit

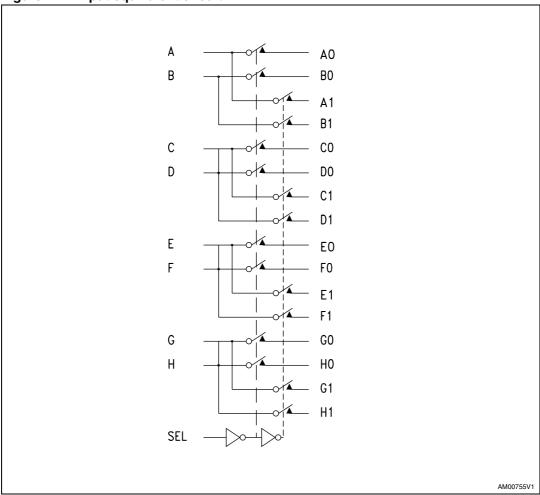


Table 3. Switch function table

SE	Function	
L	8 bit bus to 8 bit multiplexed bus 0	
H 8 bit bus to 8 bit multiplexed bus 1		

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Maximum rating ST3DV520

2 Maximum rating

Stressing the device above the rating listed in the "Absolute Maximum Ratings" table may cause permanent damage to the device. These are stress ratings only and operation of the device at these or any other conditions above those indicated in the Operating sections of this specification is not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability. Refer also to the STMicroelectronics SURE Program and other relevant quality documents.

2.1 Absolute maximum rating

Table 4. Absolute maximum ratings

Symbol	Symbol Parameter		Unit
V _{CC}	Supply voltage to ground	-0.5 to 4	V
V _I	V _I DC input voltage		V
V _{IC}	DC control input voltage	-0.5 to 4	V
I _O	DC output current ⁽¹⁾	120	mA
P _D	Power dissipation	0.5	W
T _{stg}	Storage temperature	-65 to 150	°C
T _L	Lead temperature (10 sec)	300	°C

^{1.} If $V_{IO} \times I_{O}$ does not exceed the maximum limit of P_{D} .

Table 5. DC electrical characteristics ($T_A = -40 \text{ to } 85^{\circ}\text{C}$, $V_{CC} = 3.3 \text{ V} \pm 10\%$)

Symbol	Parameter	Test conditions	Min	Тур	Max	Unit
V_{IH}	Voltage input high	High level guaranteed	2			V
V_{IL}	Voltage input low	Low level guaranteed	-0.5		0.8	٧
V _{IK}	Clamp diode voltage	$V_{CC} = 3.6 \text{ V}, I_{IN} = -18 \text{ mA}$		-0.8	-1.2	٧
I _{IH}	Input high current	$V_{CC} = 3.6 \text{ V}, V_{IN} = V_{CC}$			±5	μΑ
I _{IL}	Input low current	V _{CC} = 3.6 V, V _{IN} = GND			±5	μΑ
l _{OFF}	Power down leakage current	$V_{CC} = 0 \text{ V, A to H}$ V = 0 V, A0 to H0 and A1 to H1 \leq 3.6 V			±5	μА
R _{ON}	Switch ON resistance ⁽¹⁾	V_{CC} = 3.0 V, V_{IN} = 1.5 to V_{CC} I_{IN} = -40mA		5.5	7.5	Ω

ST3DV520 Maximum rating

Table 5. DC electrical characteristics ($T_A = -40 \text{ to } 85^{\circ}\text{C}$, $V_{CC} = 3.3 \text{ V} \pm 10\%$) (continued)

Symbol	Parameter	Test conditions	Min	Тур	Max	Unit
R _{FLAT}	ON resistance flatness ⁽¹⁾⁽²⁾	V_{CC} = 3.0 V, V_{IN} at 1.5 and V_{CC} I_{IN} = -40mA		0.8		Ω
ΔR _{ON}	ON resistance match between channel $\Delta R_{ON} = R_{ONMAX} - R_{ONMIN}$ (1)(3)	V_{CC} = 3.0 V, V_{IN} = 1.5 to V_{CC} I_{IN} = -40mA		0.5	1	Ω

Measured by voltage drop between channels at indicated current trough the switch. ON resistance is determined by the lower of the voltage.

Table 6. Capacitance specifications ($T_A = 25^{\circ}C$, f = 1 MHz)

Symbol	Parameter	Test conditions	Min	Тур	Max	Unit
C _{IN}	Input capacitance ⁽¹⁾	V _{IN} = 0 V		2	3	pF
C _{OFF}	Port x0 to Port x1, switch off	V _{IN} = 0 V		4	6	pF
C _{ON}	Capacitance switch on (x to x0 or x to x1)	V _{IN} = 0 V		7.5	11	pF

^{1.} x = A to H, x0 = A0 to H0, x1 = A1 to H1

Table 7. Power supply characteristics $(T_A = -40 \text{ to } 85^{\circ}\text{C})$

Symbol	Parameter	Test conditions	Min	Тур	Max	Unit
I _{CC}	Quiescent power supply	$V_{CC} = 3.6 V$ $V_{IN} = V_{CC} \text{ or GND}$		150	500	μΑ

Table 8. Dynamic electrical characteristics ($T_A = -40 \text{ to } 85^{\circ}\text{C}$, $V_{CC} = 3.3\text{V} \pm 10\%$)

Symb ol	Parameter	Test Conditions	Min	Тур	Max	Unit
X _{talk}	Crosstalk	$R_L = 100 \Omega$, $f = 250 MHz$		-40		dB
O _{IRR}	Off isolation	R_L = 100 Ω, f = 250 MHz		-36		dB
BW	-3dB bandwidth	R _L = 100 Ω		450		MHz

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Flatness is defined as the difference between the R_{ONMAX} and R_{ONMIN} of ON resistance over the specified range.

^{3.} ΔR_{ON} measured at same $V_{CC},$ temperature and voltage level.

Maximum rating ST3DV520

Table 9. Switching characteristics ($T_A = -40 \text{ to } 85^{\circ}\text{C}$, $V_{CC} = 3.3\text{V} \pm 10\%$)

Symb ol	Parameter	Test conditions	Min	Тур	Max	Unit
t _{PD}	Propagation delay	V _{CC} = 3 V to 3.6 V		0.25		ns
t _{PZH} , t _{PZL}	Line enable time, SE to x to x0 or x to x1	V _{CC} = 3 V to 3.6 V	0.5	6.5	9	ns
t _{PHZ} , t _{PLZ}	Line disable time, SE to x to x0 or x to x1	V _{CC} = 3 V to 3.6 V	0.5	6.5	8.5	ns
t _{SK(O)}	Output skew between center port to any other port	V _{CC} = 3 V to 3.6 V		0.1	0.2	ns
t _{SK(P)}	Skew between opposite transition of the same output (t _{PHL} , t _{PLH})	V _{CC} = 3 V to 3.6 V		0.1	0.2	ns

Note 4: x = A to H, x0 = A0 to H0, x1 = A1 to H1.

Figure 3. Bandwidth

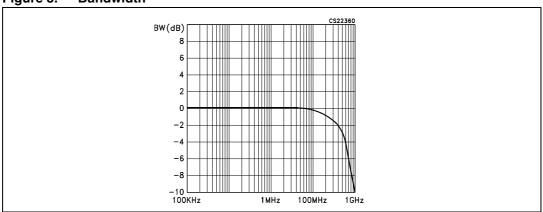
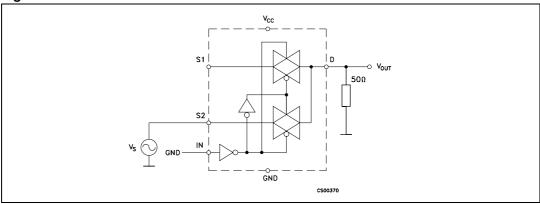


Figure 4. Schematic bandwidth



3 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK[®] packages. These packages have a Lead-free second level interconnect. The category of second Level Interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com.

BIN 1 D2 D2 EXPOSED PAD

SENTIFICATION

1 2 3

BON 1 D2

20

EXPOSED PAD

1 2 1 C

EXPOSED PAD

1 2 1 C

A 3

SEATING PLANE

E/2

TOTAL SCALE

TOTAL

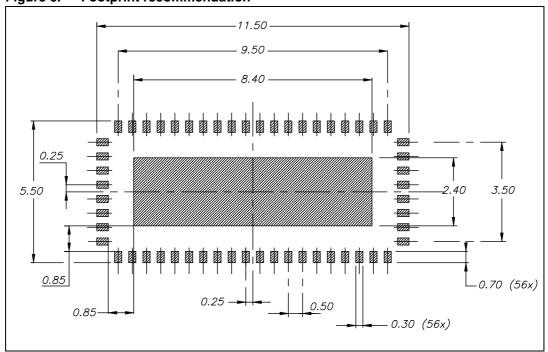
Figure 5. QFN56 (11 x 5 mm) package outline

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Table 10. QFN56 (11 x 5 mm) mechanical data

Complete		millimeters			inches	
Symbol	Min	Тур	Max	Min	Тур	Max
Α	0.70	0.75	0.80	0.028	0.030	0.031
A1			0.05			0.002
A3		0.20			0.008	
b	0.20	0.25	0.30	0.008	0.010	0.012
D	10.90	11.00	11.10	0.429	0.433	0.437
D2	8.30	8.40	8.50	0.327	0.331	0.335
D3		9.50			0.374	
Е	4.90	5.00	5.10	0.193	0.197	0.201
E2	2.30	2.40	2.50	0.091	0.094	0.098
E3		3.50			0.138	
е		0.50			0.020	
L	0.30	0.40	0.50	0.012	0.016	0.020

Figure 6. Footprint recommendation



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ST3DV520 Revision history

4 Revision history

Table 11. Document revision history

Date	Revision	Changes	
12-Jun-2007	1	Initial release.	
09-Oct-2008 2		Modified: title and pinout configuration. Added: Figure 6: Footprint recommendation on page 8.	

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